

Delphi Mini USB Connectors

Description – Board mount I/O connectors for the industry standard USB (Universal Serial Bus) interface used to connect high speed peripheral devices to computers. Mini USBs are ideal for applications that require small, lightweight connectors.

Typical Applications –

- Desktop and notebook computers
- Digital cameras
- PDAs, cell phones
- External disk drives
- Portable music recorders/players

Benefits/Features:

Industry Standard . . . Meets the speed requirements of USB 2.0.

Meets preliminary requirements of USB OTG (On-The-Go).

Flexible System . . . SMT and through hole mounting styles are available.

Allows for hot plugging of multiple devices.

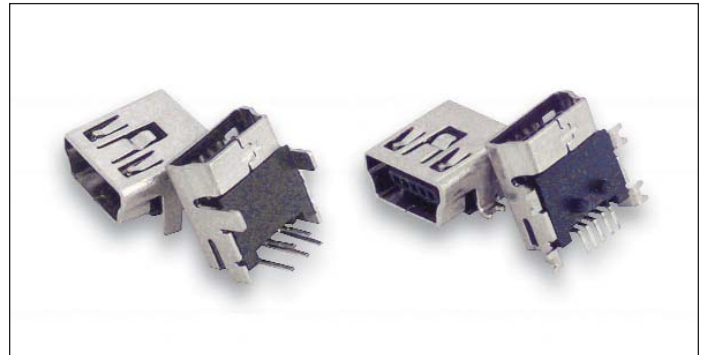
Ruggedness

and Reliability . . . Full metal shields help protect contacts from physical and ESD (Electro Static Discharge) damage.

High cycle life versions are available.

Selectable Features

Product Type	Mini B USB receptacles
Total No. of Positions	5
Centerline Spacing	0.8 mm [.0315 in.]
Orientation	Horizontal
Mounting Style	DIP or SMT
Operating Voltage	30 VAC RMS
PCB Thickness	SMT: N/A, TH: 0.8 mm [.0315 in.]
Contact Style	Formed
Contact Area Plating	Gold plated (see product print for thickness)
Height Above Board	4 mm [.16 in.]
Shell (Shield) Material	Brass
Housing Color	Black



Other Properties

Packaging Type	SMT: tape and reel, Through hole: tray
Housing Material	Nylon GF
Applicable Soldering Process	IR, vapor phase, wave
Contact Base Material	Phosphor bronze
Insulation Resistance	100 M Ω initial
Withstanding Voltage	100 VAC RMS
Current Rating	1 amp max. per contact
Contact Resistance	30 m Ω
Temperature Range	-25°C to +70°C
Normal Force	30 g min. (controlled by cable connector)
Durability (Mating Cycles)	5000 cycles
Mating Force	35 N [7.9 lbf] max.
Unmating Force	7 N [1.6 lbf] min. initial
Plating (Contact Area)	Gold (thickness varies per Delphi spec.) over nickel underplating
Plating (Soldering End)	2.03 μ m [80 μ in.] min. tin-lead over nickel underplating
Plating (Shield)	2.03 μ m [80 μ in.] min. tin-lead over nickel underplating
Underplating	1.27 μ m [50 μ in.] nickel
Standards	Universal Serial Bus Revision 2.0 Specification USB 2.0 Specification ECN #1: Mini B Connector
Approvals and Certification	UL approved

DELPHI

www.delphi.com/connect

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Ordering Nomenclature

1543 0262 - 1 0 0

Surface Mount . . **1543 0262**
Through Hole . . . **1543 0384**

Selective Plating:

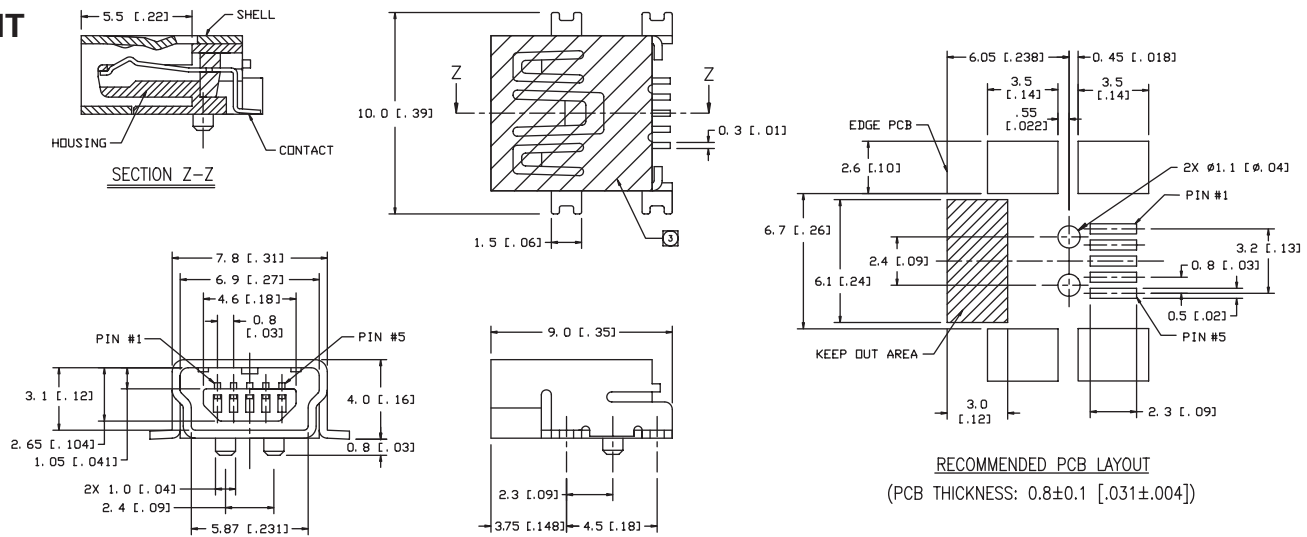
Gold plated on contact area and 2.54 μm [100 $\mu\text{in.}$] min. tin-lead plated on soldering end over 1.27 μm [50 $\mu\text{in.}$] min. nickel underplating

1 = Gold Flash

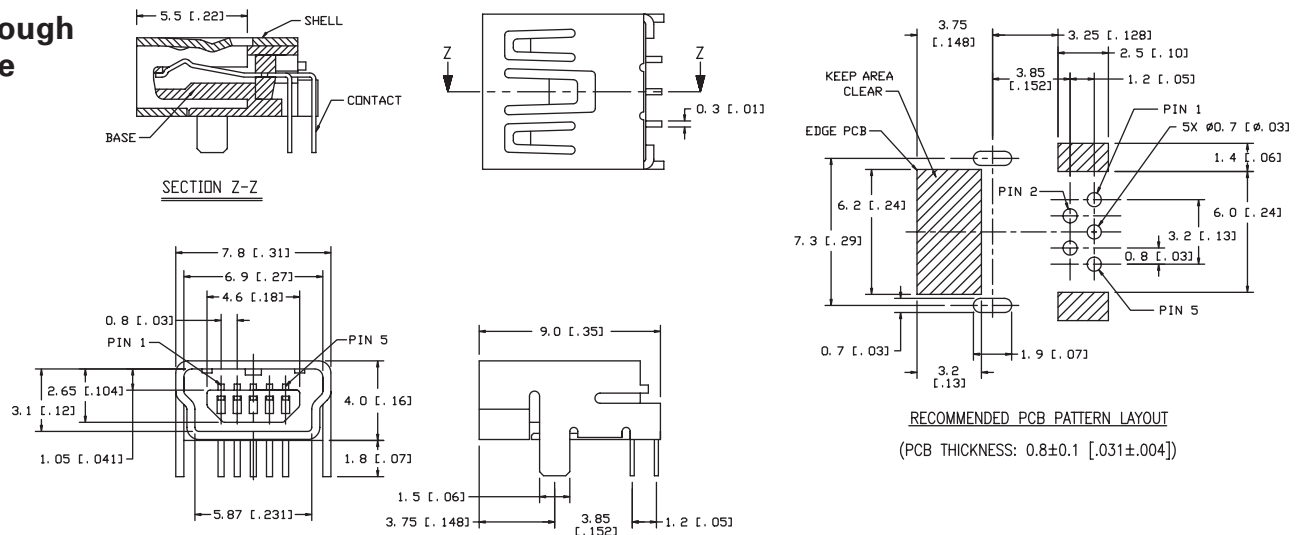
2 = 0.381 μm [15 $\mu\text{in.}$]

3 = 0.762 μm [30 $\mu\text{in.}$]

SMT



Through Hole



Dimensions are in millimeters and [inches].